Special Issue

Deep Learning-Enhanced Structural Health Monitoring

Message from the Guest Editors

This Special Issue calls for high-quality original research articles, review articles, and technical notes focused on such emergent technologies and the latest advances in the field. Topics may cover broad areas related to the development or enhancement of applied methodologies, new SHM architectures, wireless sensing networks, smart devices, optimal sensors placement, issues related to structural implementation, synthetic data generation and processing, and interdisciplinary applications. Special Issue Link: https://www.mdpi.com/journal/applsci/special_issues/3U7HAO4J6T

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Deadline for manuscript submissions

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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